

Advanced Packaging Update: Market and Technology Trends

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This issue of the Advanced Packaging Update features a detailed financial analysis of the top 20 OSATs. The impact of data center growth on package demand is discussed. Build-up substrate capacity and demand is presented with an analysis of the crisis caused by body size growth. Market forecasts for ball grid arrays (BGAs) and chip scale packages (CSPs) are provided in units. The CSP market is divided into laminate (FBGA and FLGA) and leadframe (QFN) substrates. Stacked die package are included.

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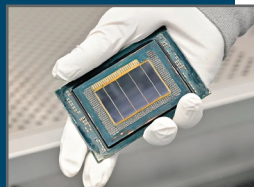
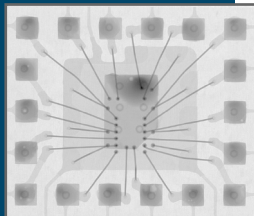
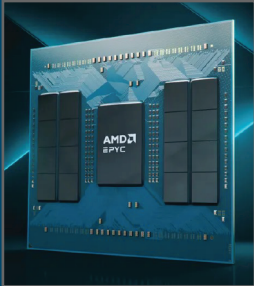
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